

IN THE SPECIFICATION:

Please amend paragraph [0033] on pages 18-19 as follows:

Intermediate insulating layer 4 is disposed between upper piezo-electric active layer 5 and lower piezo-electric active layer 6. Upper insulating layer 2 is disposed on a surface of upper piezo-electric active layer 5 opposite to a surface on which intermediate insulating layer 4 is disposed, and lower insulating layer [[6]] 3 is disposed on a surface of lower piezo-electric active layer 6 opposite to a surface on which intermediate insulating layer 4 is disposed. Upper insulating layer 2 constitutes a top layer of piezo-electric ceramic transducer 1, and lower insulating layer 3 constitutes a lowest layer of piezo-electric ceramic transducer 1.

Please amend paragraph [0036] on page 20 as follows:

By sintering the layers constituting piezo-electric ceramic transducer 1 after the staking stacking of the layers in a multilayered structure, thickness and weight of a sintered object become large as compared with a case where each of the layers are separately sintered. As a result, a degree of sintering distortion in a sintering process becomes considerably lowered, so that a mechanical working process such as grinding and polishing can become unnecessary after sintering. Further, because integration of the layers is obtained by sintering, a joining process for joining the layers to each other for integration of the layers is unnecessary. Therefore, a manufacturing process for piezo-electric ceramic transducer 1 is reduced, so that piezo-electric ceramic transducer 1 can

be manufactured at low cost. Further, because there are no portions joined with adhesives in boundary portions of the layers, reliability against mechanical breakage is improved.